

Product / Process Change Notification



N° 2021-022-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Introduction of an additional wafer production location at Infineon Technologies Austria AG, Villach, Austria and introduction of an additional assembly and final test location at Huayi Microelectronics Co., Ltd (HYME), for package TO220 for CoolMOS™ P7 600V and 700V products

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **21. April 2021**.
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JEESD46**“, which stipulates:
“**Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.**”

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
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Chairman of the Supervisory Board: Dr. Wolfgang Eder
Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Dr. Sven Schneider
Registered Office: Neubiberg
Commercial Register: München HRB 126492

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► **Products affected:**

Please refer to attached affected product list 1_cip21022_a



► **Detailed Change Information:**

Subject: Introduction of an additional wafer production location at Infineon Technologies Austria AG, Villach, Austria and introduction of an additional assembly and final test location at Huayi Microelectronics Co., Ltd (HYME), for package TO220 for CoolMOS™ P7 600V and 700V products

Reason: Introduction of additional wafer production location at Infineon Technologies Austria AG, Villach, Austria and additional as additional assembly and final test location at Huayi Microelectronics Co., Ltd (HYME), for package TO220 as additional capacity to ensure continuity of supply and enable flexible manufacturing

Description:	Old		New	
Wafer Production Location	■ Infineon Technologies Dresden GmbH & Co. KG		■ Infineon Technologies Dresden GmbH & Co. KG	
			Or	■ Infineon Technologies Austria AG
TO220 Assembly and Test Location	■ ASE (Weihai) Inc., China		■ ASE (Weihai) Inc., China	
	Or		Or	
	■ Infineon Technologies (Malaysia) Sdn. Bhd		■ Infineon Technologies (Malaysia) Sdn. Bhd	
			Or	■ Huayi Microelectronics Co., Ltd (HYME) in Xi'An,

► **Product Identification:**

Traceability via Baunumber, Lotnumber

External traceability: Product Barcode Label

► **Impact of Change:**

NO change on electrical and thermal performance
NO impact on the device reliability as proven via product qualification.
NO impact on the electrical parameters and device processability at customer end.

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- The package outer dimensions remain unchanged

► Attachments:

Affected product list : 1_cip21022_a
Qualification Test Report : 2_cip21022_a
Customer Info Package : 3_cip21022_a

► Time Schedule:

- | | |
|-------------------------------|---|
| ■ Final qualification report: | available |
| ■ First samples available: | on request |
| ■ Intended start of delivery: | 01-September-2021 or earlier upon customer approval |

If you have any questions, please do not hesitate to contact your local Sales office.